



Final Product Change Notification

202106031F01 : AFIC901N Assembly Transfer

Note: This notice is NXP Company Proprietary.

Issue Date: Jan 19, 2022 **Effective date:** Apr 19, 2022

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Management summary

AFIC901N Assembly Transfer

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

NXP is pleased to announce assembly transfer of product AFIC901NT1 to a new assembly location. This assembly transfer ensures NXP capacity to manufacture this product to meet customer demand. This assembly transfer will use exact process of record (POR) semiconductor die. The only difference will be that new Site Lead Frame will have slightly different Center Pad dimension before mold while maintaining same nominal dimension after mold. See attached document with details of critical dimension and gap comparison of Current Lead Frame vs. New Lead Frame. No other difference has been identified.

Reason

Assembly transfer to ensure customer supply.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Apr 19, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

No Reliability or Quality Risks have been identified. No change on Form or Function. New Lead Frame has slightly different central Pad dimension, as shown on attached document. The specification for exposed pad after mold is unchanged.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Feb 18, 2022.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
AFIC901NT1	935313071547	AFIC901NT1	2W 7.5V QFN4X4-24	H(V)QFN24	SOT616-6	RF5	No	BLRF